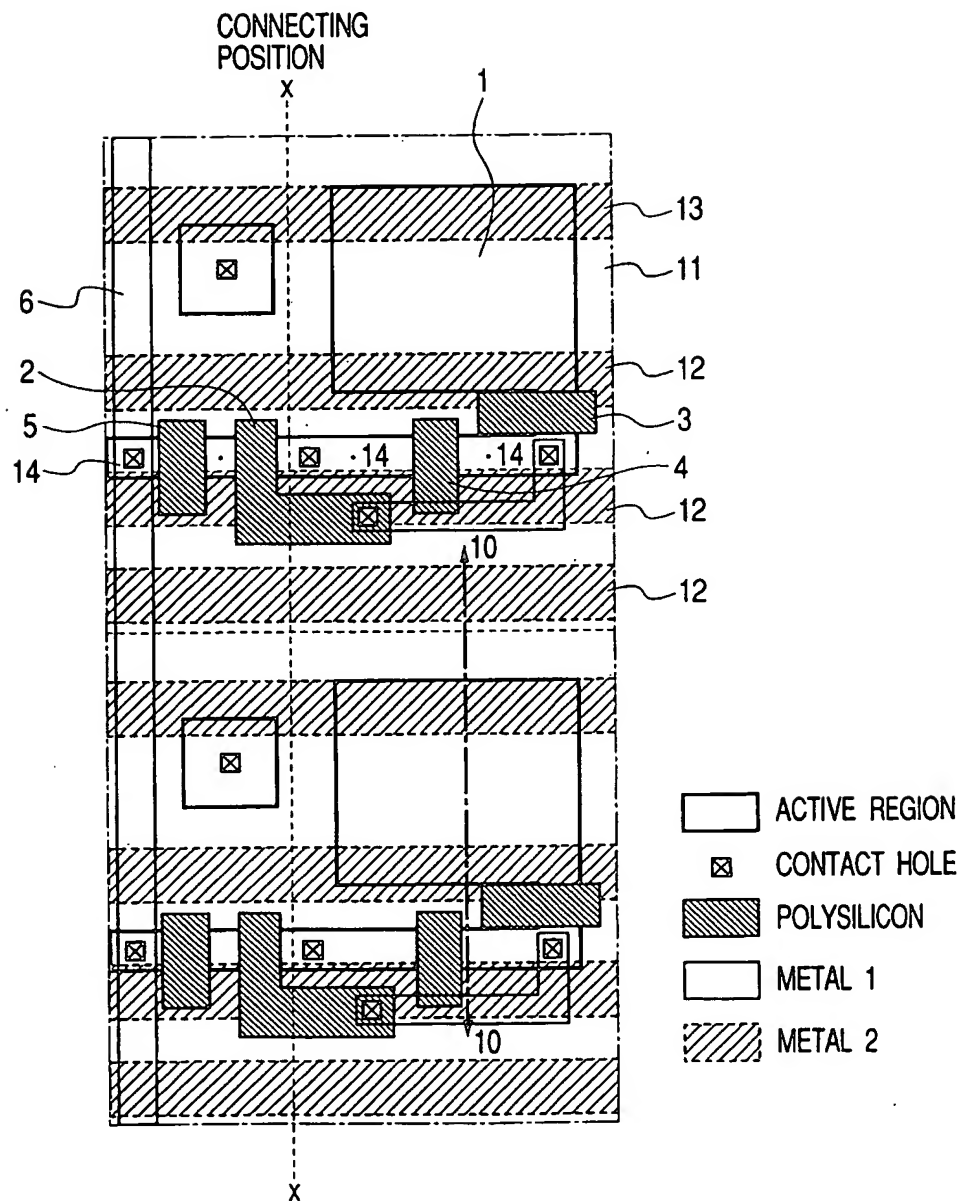
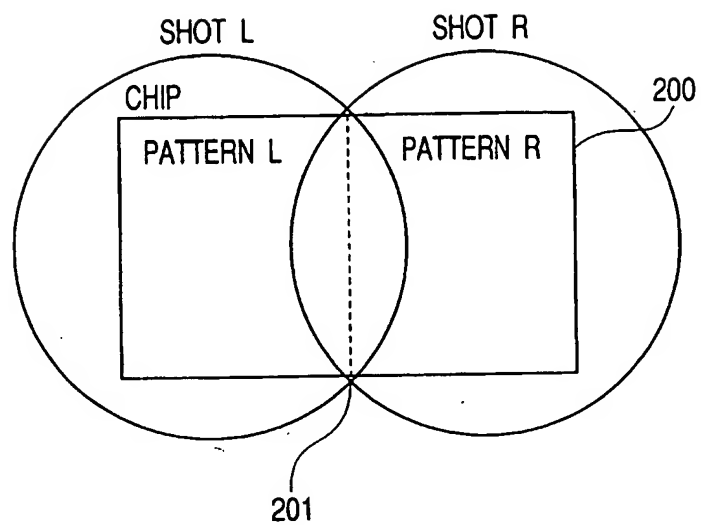


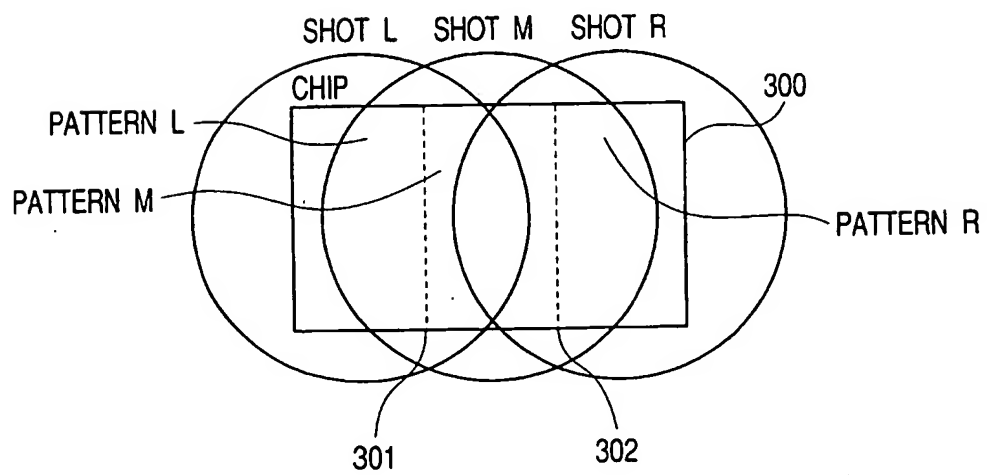
FIG. 1



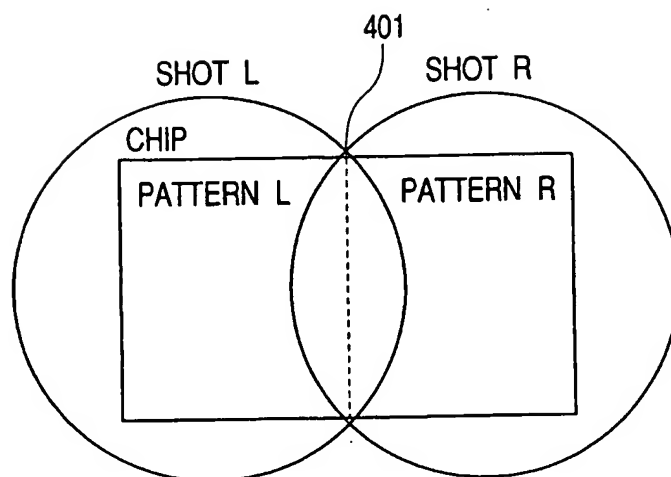
**FIG. 2**



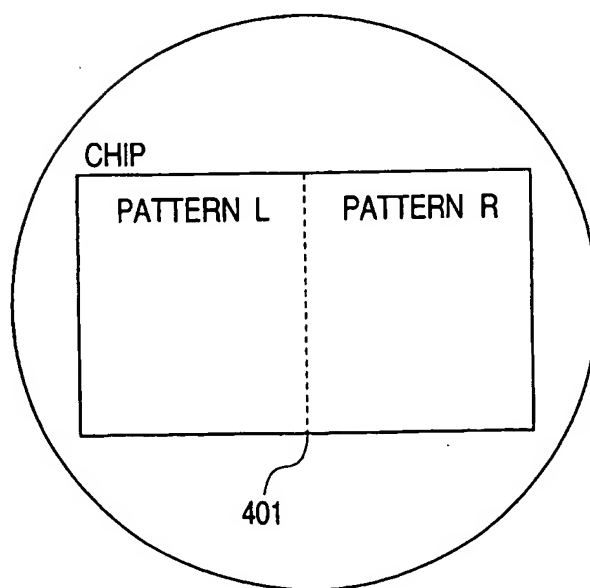
**FIG. 3**



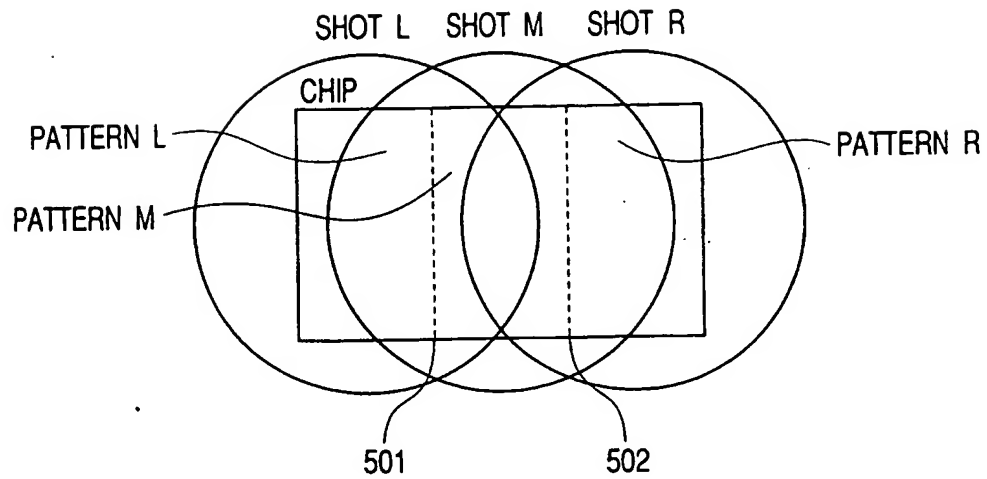
**FIG. 4A**



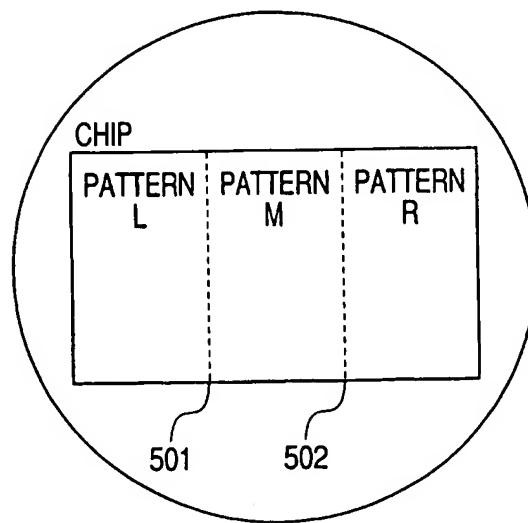
**FIG. 4B**



**FIG. 5A**



**FIG. 5B**



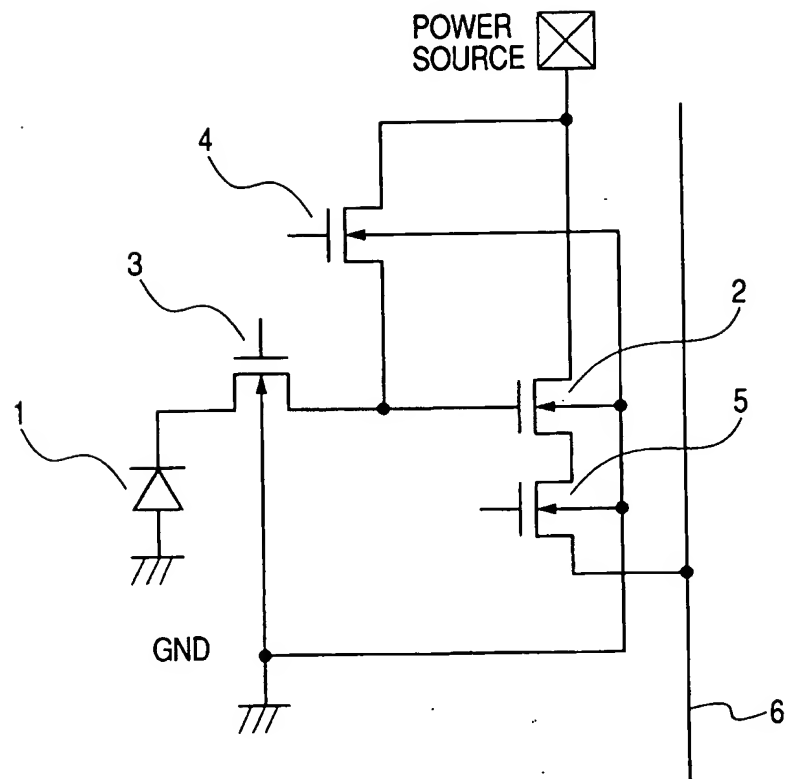
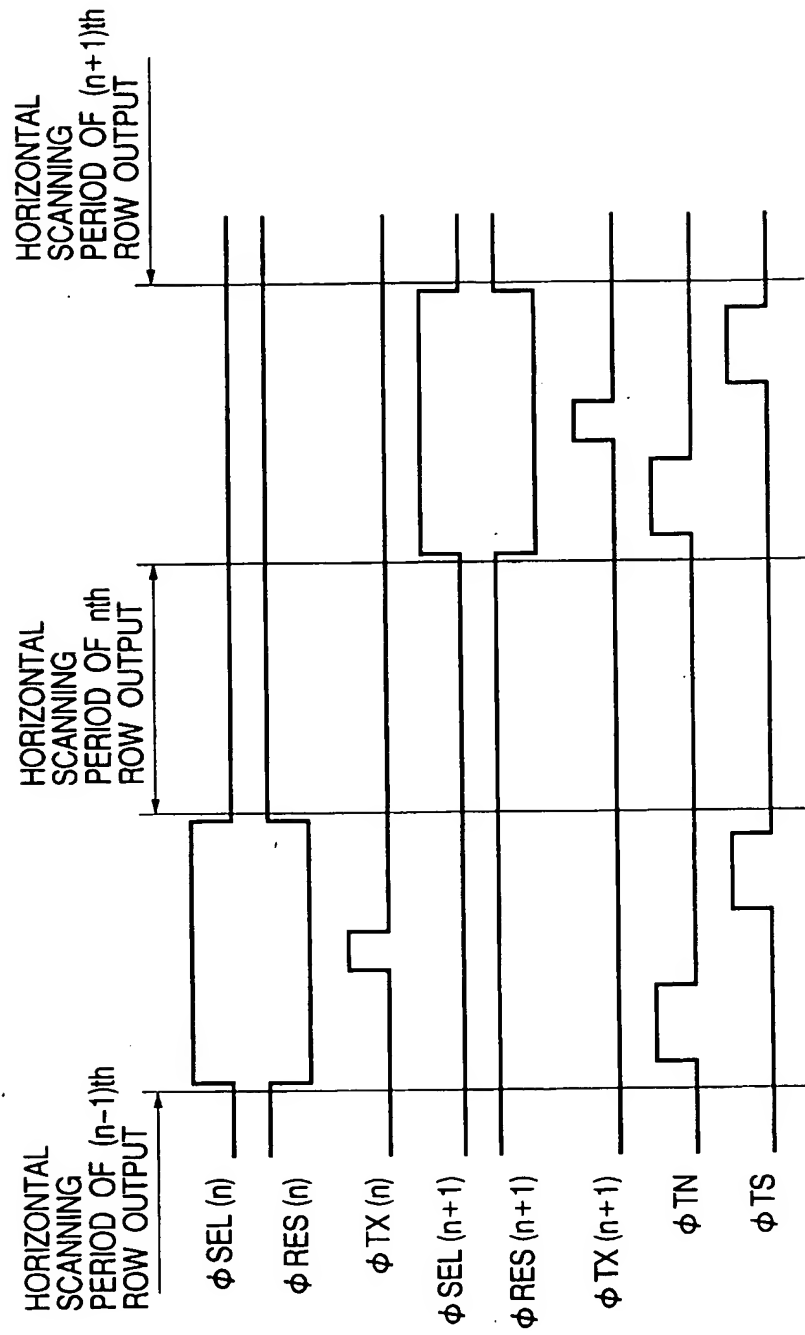
*FIG. 6*



FIG. 8



**FIG. 9**

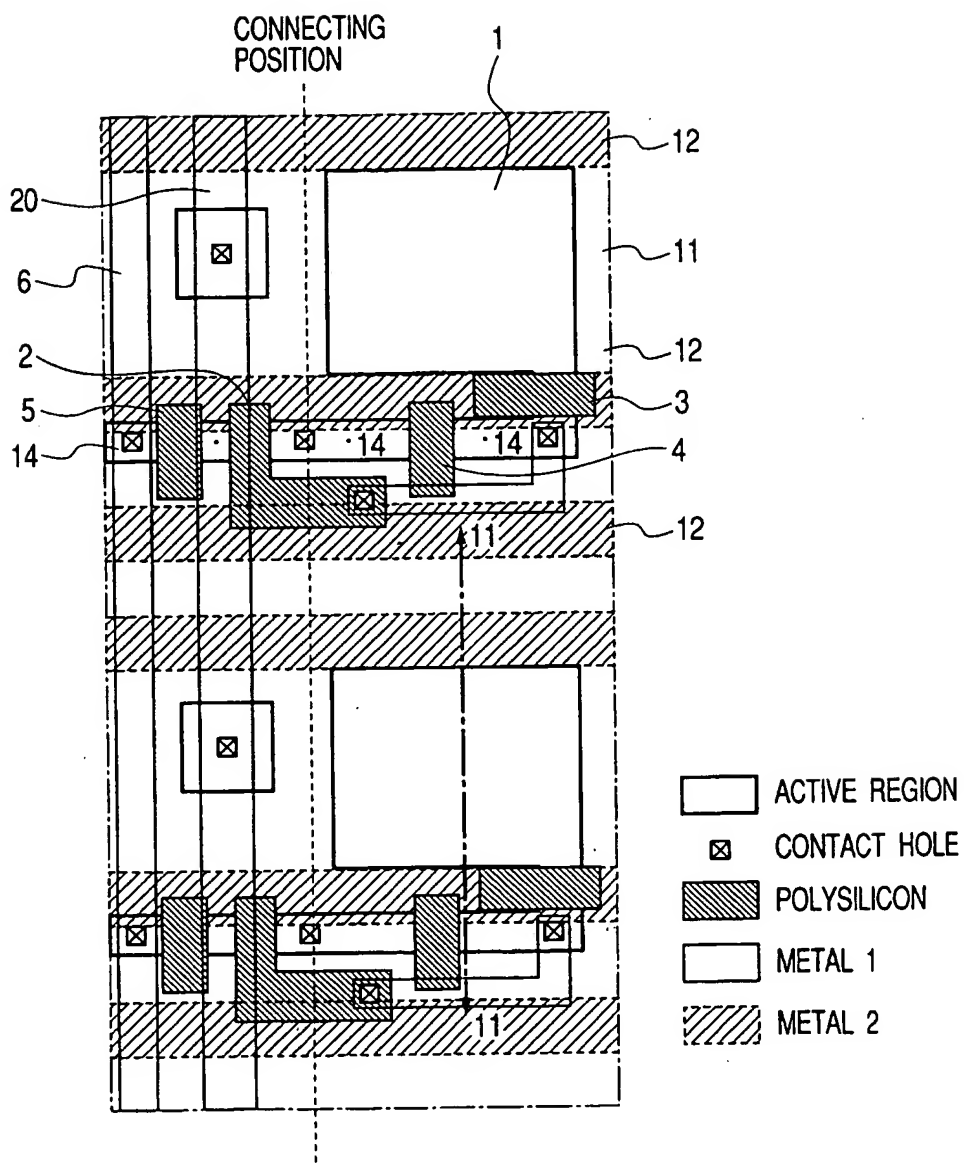




FIG. 10B

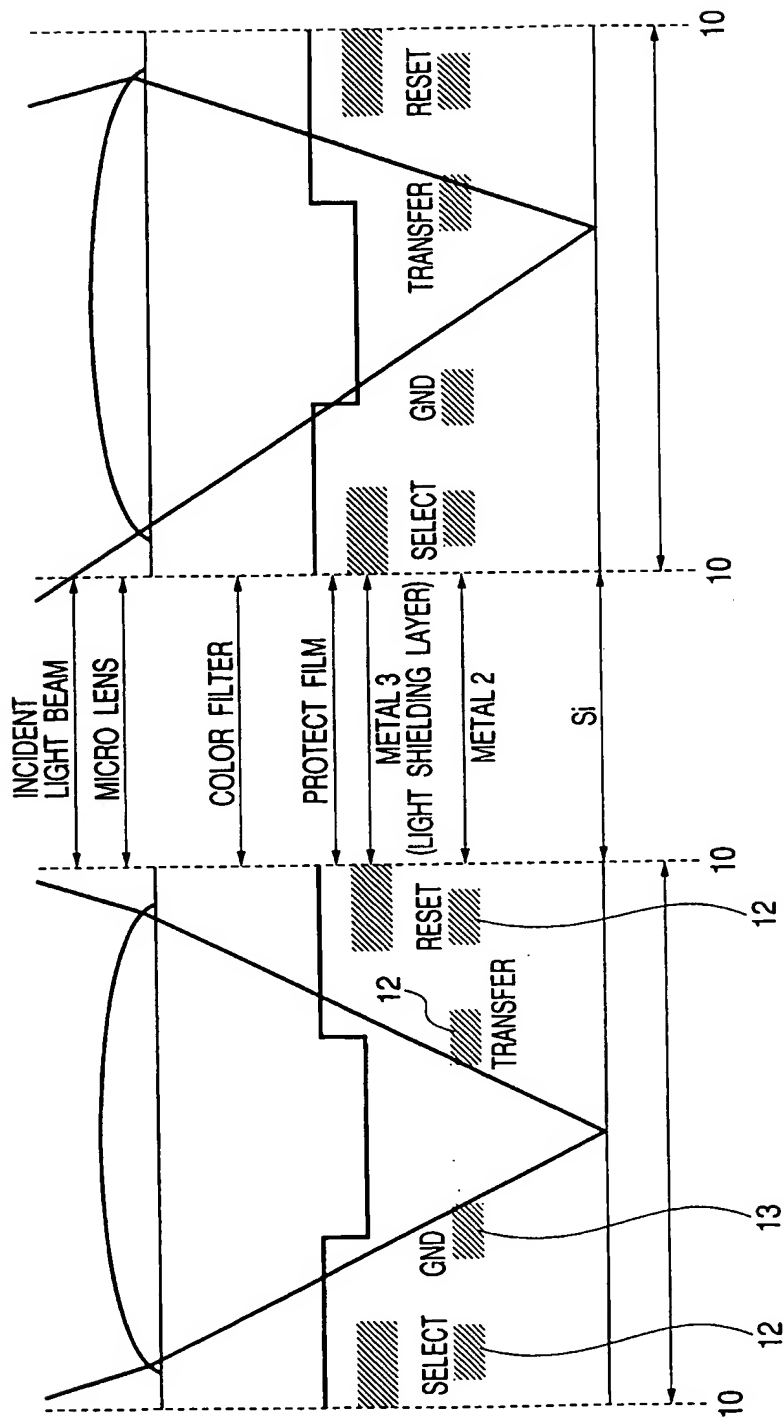


FIG. 10A

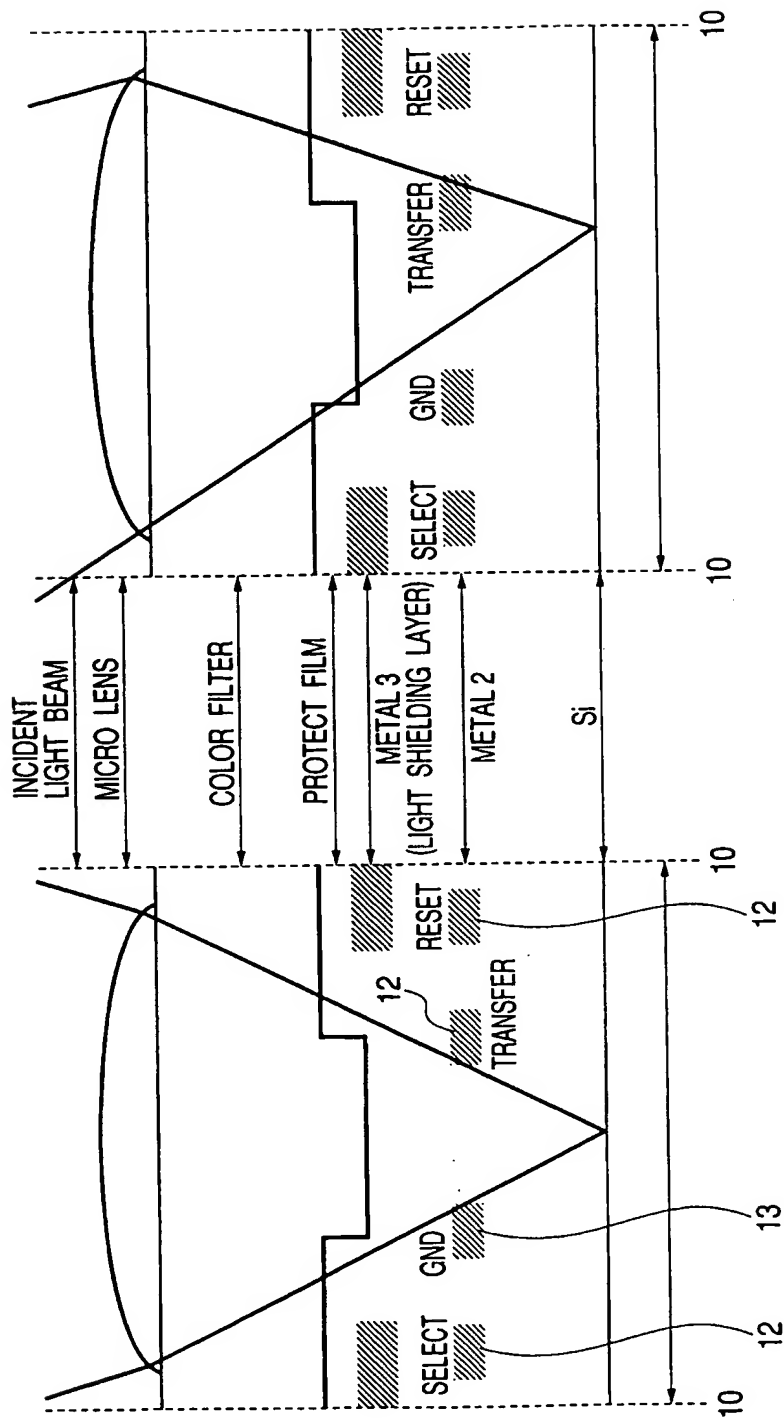


FIG. 11B

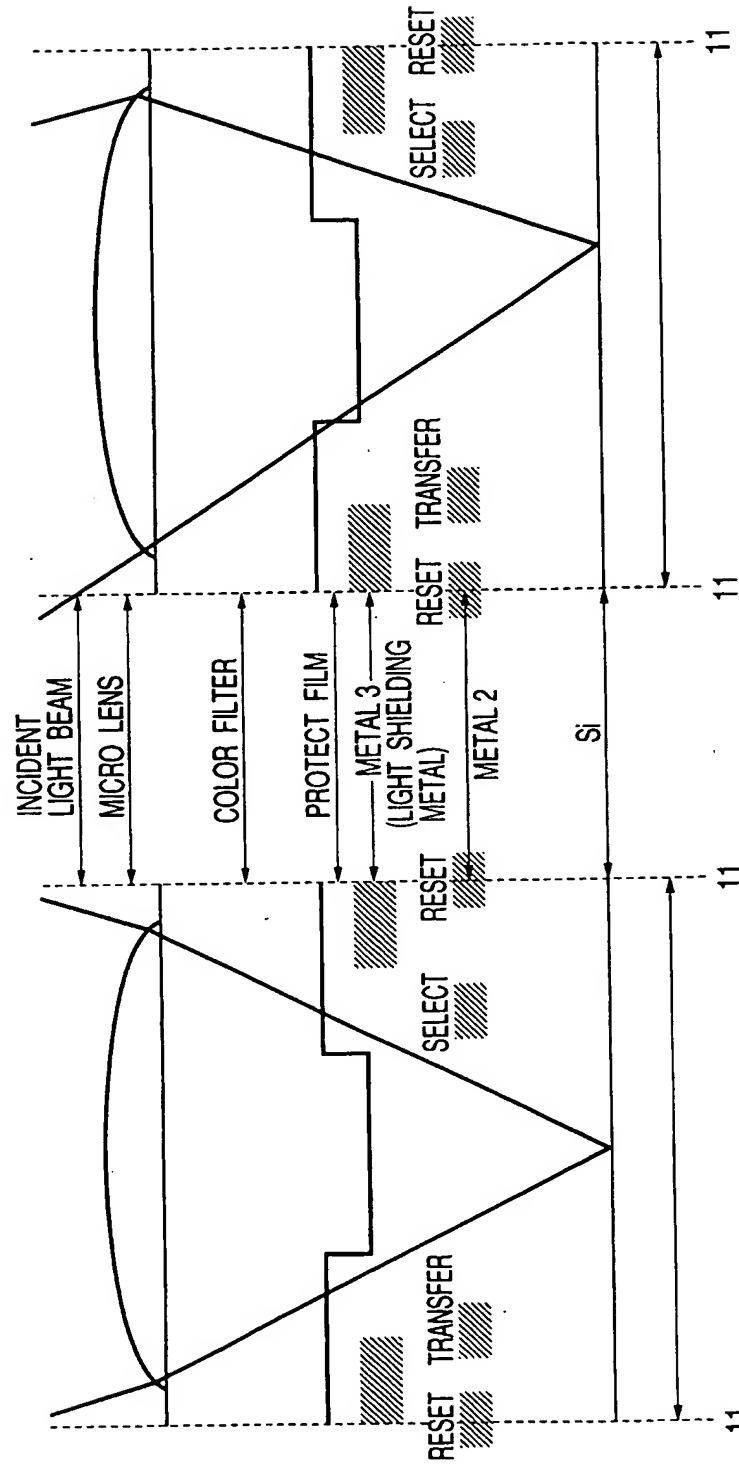
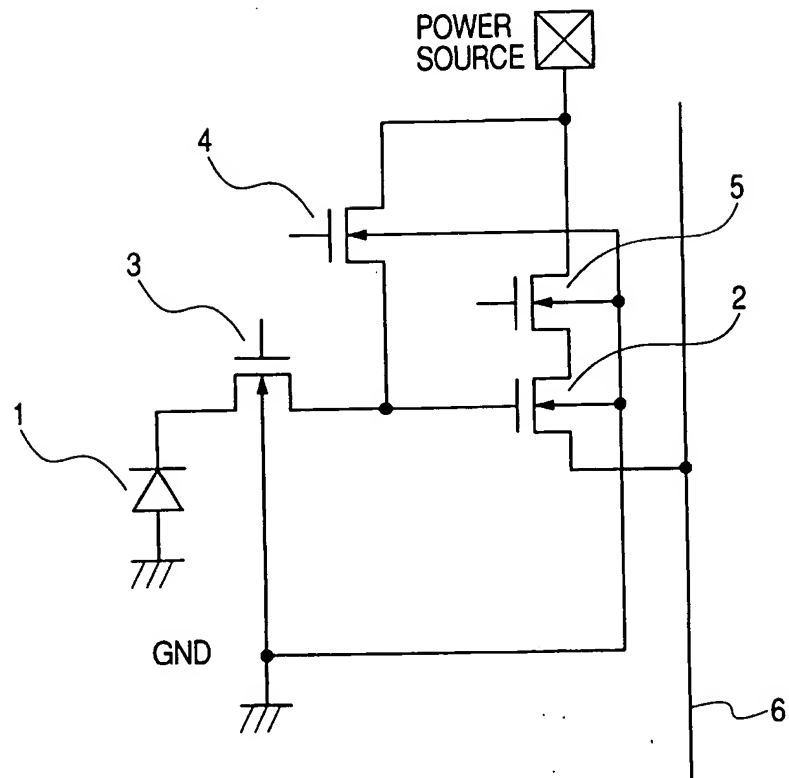
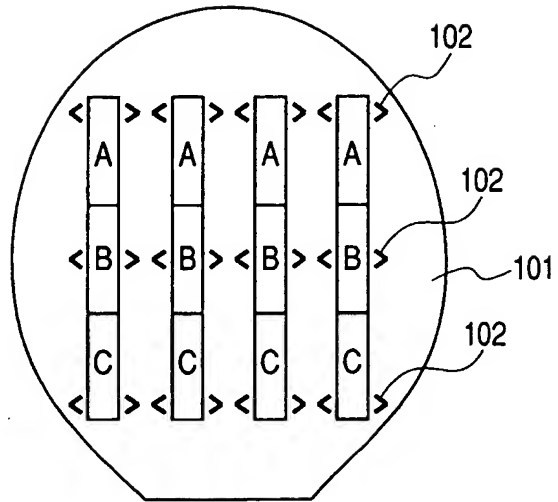


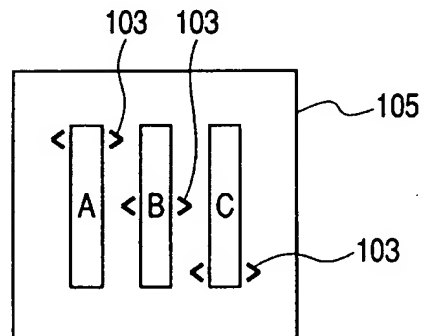
FIG. 11A

*FIG. 12*

**FIG. 13A**



**FIG. 13B**



**FIG. 13C**

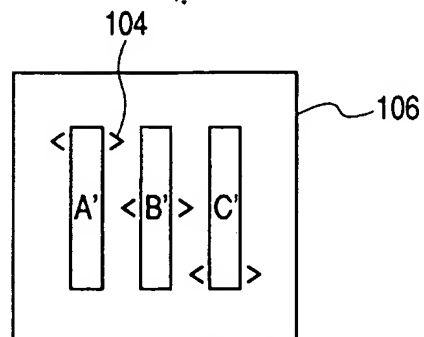
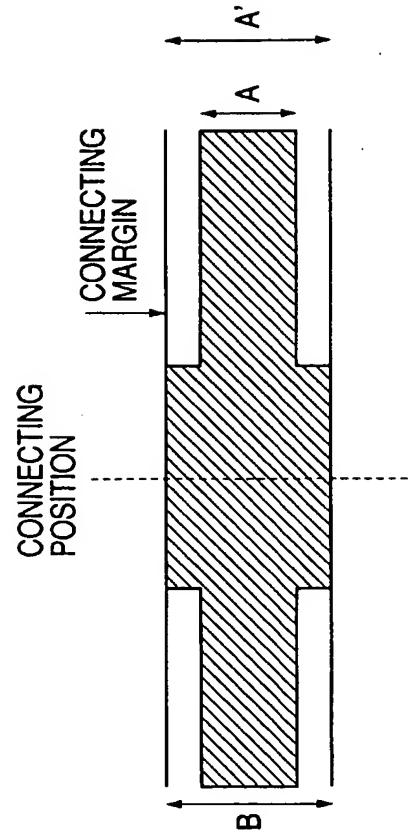


FIG. 14



A : WIRING WIDTH FORMED BY EXPOSURE USING REDUCTION PROJECTING APPARATUS FOR MICROMINIATURE WORKING

A' : WIRING WIDTH FORMED BY DIVISIONAL EXPOSURE (USING CONNECTING MARGIN)

B : WIRING WIDTH FORMED BY BATCH PROCESSING OF EXPOSURE USING REDUCTION PROJECTING APPARATUS OF LARGE EXPOSURE AREA